

ABSTRACT

A method of making a semiconductor chip assembly includes providing a semiconductor chip, a conductive trace and a substrate, wherein the chip includes first and second opposing major surfaces and a conductive pad, the pad extends to the first 5 surface of the chip, the substrate includes first and second opposing major surfaces, a conductive terminal and a dielectric base, the conductive terminal extends through the dielectric base to the first and second surfaces of the substrate, a cavity extends from the first surface of the substrate into the substrate, the first surfaces of the chip and the substrate face in a first direction, the second surfaces of the chip and the substrate face 10 in a second direction, and the chip extends into the cavity, and then electrically connecting the conductive terminal to the pad using the conductive trace.